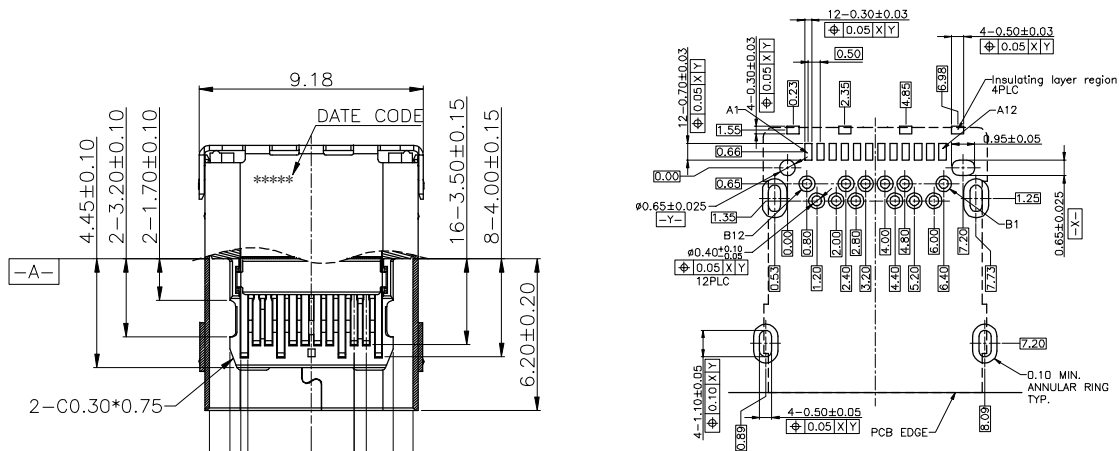


REV.	ECN NO.	CONTENT	DATE	ENGINEER
X0			2015 01/08	Lengqiang

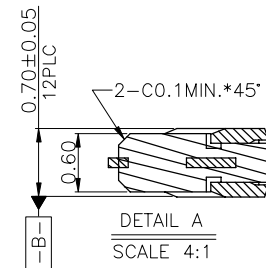
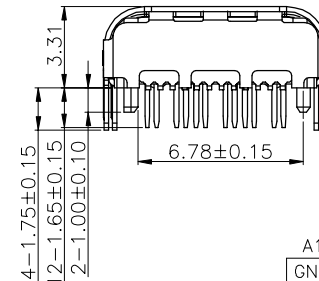
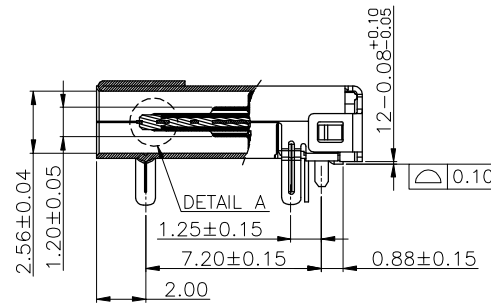
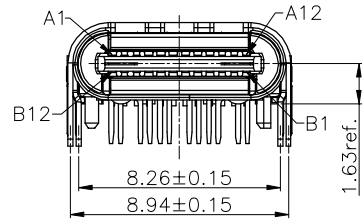


RECOMMENDED PCB LAYOUT (COMPONENT SIDE)

NOTE:

- PRODUCT MUST COMPLY WITH THE ENVIRONMENTAL PROTECTION STANDARD OF BIZCONN.
- MATERIAL:
  - MOLDING HOUSING:HIGH TEMPERATURE THERMOPLASTIC UL94-V0,BLACK,HF.
  - TERMINAL:COPPER ALLOY.
  - SHELL:STAINLESS STEEL.
- FINISH:
  - TERMINAL: GOLD-PLATED ON CONTACT AREA SEE P/N NOETS,SOLDER AREA Sn 100u", Ni 50u" UNDERPLATED ALL OVER.
  - SHELL: Ni 50u" MIN PLATED ALL OVER.
- SOLDER TEMPERATURE IS 260°C±5°C.
- THE P/N IS SHOWN AS BELOW.
- DATE CODE: DESCRIPTION OF THE D/C:

\*\* \*\* \*  
DATE(MONDAY~SUNDAY:1~7)  
WEEK(27: THE 27TH WEEK)  
YEAR(13: 2013)



DETAIL A  
SCALE 4:1

A1	A2	A3	A4	A5	A6	A7	A8	A9	A10	A11	A12
GND	TX1+TX1-VBUS	CC1	D+	D-	SBU1	VBUS	RX2-RX2+GND				
B12	B11	B10	B9	B8	B7	B6	B5	B4	B3	B2	B1
GND	RX1+RX1-VBUS	SBU2	D-	D+	CC2	VBUS	TX2-TX2+GND				

INTERFACE DEFINITION

P/N NOTES:

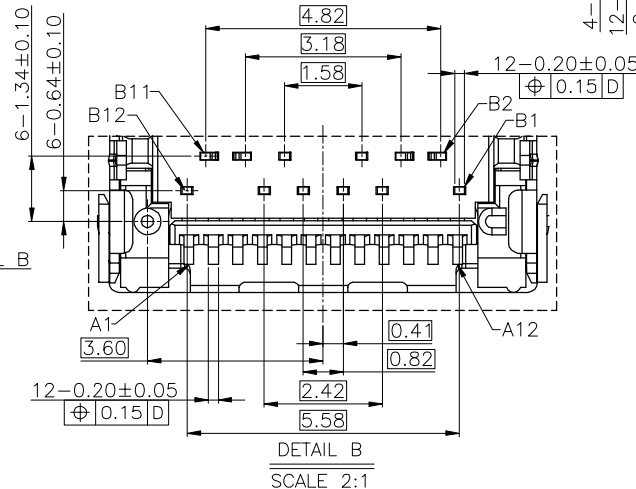
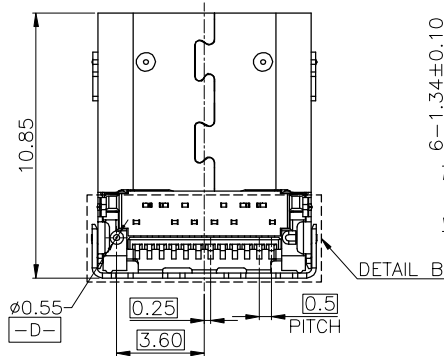
SAP P/N	TIPTOP P/N	SPECIFICATION
115H0-015755-R1	644-241000SA00000	Terminal Contact Area 15u"Au,Solder Area 100u"Sn, 50u"Ni,SHELL 50u"Ni Min,NO MARK.
115H0-015369-R1	644-241000SA01000	Terminal Contact Area 15u"Au,Solder Area 100u"Sn, 50u"Ni,SHELL 50u"Ni Min,BizLink MARK.
115H0-015273-R1	644-241000SF01000	Terminal Contact Area 30u"Au,Solder Area 100u"Sn, 50u"Ni,SHELL 50u"Ni Min,BizLink MARK.

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**BizLink**

康联精密机电(深圳)有限公司  
BizConn International Corporation

.X: ±0.38 .XX: ±0.25 .XXX: ±0.13	X': ±3' .X': ±1' .XX': ±0.5'	NAME: USB TYPE-C HYBRID R/A REC CUSTOMER DRAWING
APPD. DAX	01/08'15	DRW NO.: WDR-032-14054 SIZE: A4 PJ. NO.: 14-0014
CHKD. Hongguang	01/08'15	FINISH: SEE NOTES MAT'L.: SEENOTES
DR. Lengqiang	01/08'15	SCALE: N/A REV.: X0 UNIT: mm PAGE: 1/1



DETAIL B  
SCALE 2:1

